

Low VF Chip Schottky Barrier Diodes

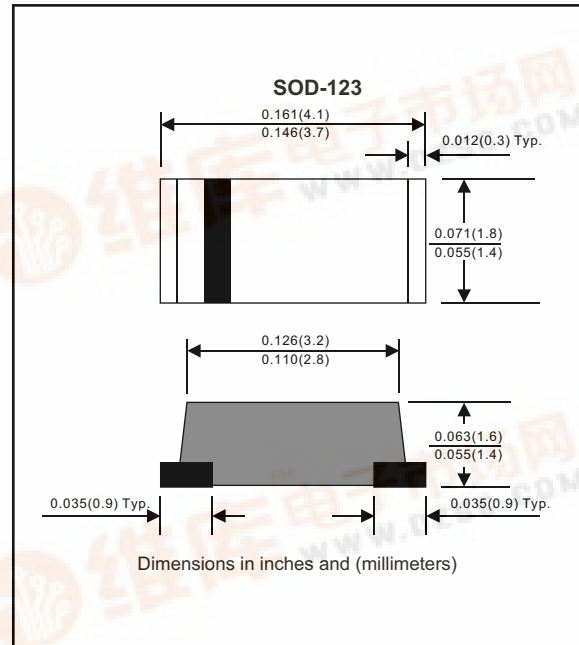
Formosa MS

SL22-M THRU SL24-M

Silicon epitaxial planer type

Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-O Utilizing Flame Retardant Epoxy Molding Compound.
- For surface mounted applications.
- Exceeds environmental standards of ML-S-19500 / 228
- Low leakage current



Mechanical data

Case : Moulded plastic, JEDEC SOD123 / MNISMA
 Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
 Polarity : Indicated by cathode band
 Mounting Position : Any
 Weight : 0.04 gram

MAXIMUM RATINGS (AT T_A=25°C unless otherwise noted)

PARAMETER	CONDITIONS	Symbol	MIN.	TYP.	MAX.	UNIT
Forward rectified current	See Fig.2	I _O			2.0	A
Forward surge current	8.3ms single half sine-wave superimposed on rate load (JEDEC methode)	I _{FSM}			50	A
Reverse current	V _R = V _{RRM} T _A = 25°C	I _R			1.0	mA
	V _R = V _{RRM} T _A = 100°C				10	mA
Thermal resistance	Junction to ambient	R _{JA}		70		°C / w
Diode junction capacitance	f=1MHz and applied 4vDC reverse voltage	C _J		160		pF
Storage temperature		T _{STG}	-55		+150	°C

SYMBOLS	MARKING CODE	V _{RRM} *1 (V)	V _{RMS} *2 (V)	V _R *3 (V)	V _F *4 (V)	Operating temperature (°C)
SL22-M	SL22	20	14	20	0.38	-55 to +125
SL23-M	SL23	30	21	30	0.40	
SL24-M	SL24	40	28	40	0.40	

*1 Repetitive peak reverse voltage

*2 RMS voltage

*3 Continuous reverse voltage

*4 Maximum forward voltage



RATING AND CHARACTERISTIC CURVES (SL22-M THRU SL24-M)

FIG.1-TYPICAL FORWARD CHARACTERISTICS

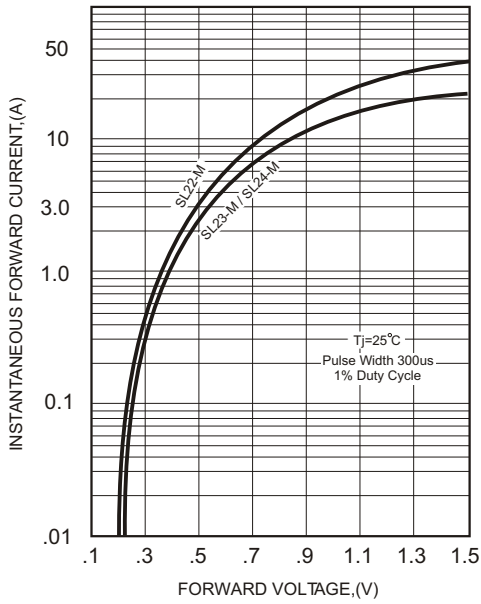


FIG.2-TYPICAL FORWARD CURRENT DERATING CURVE

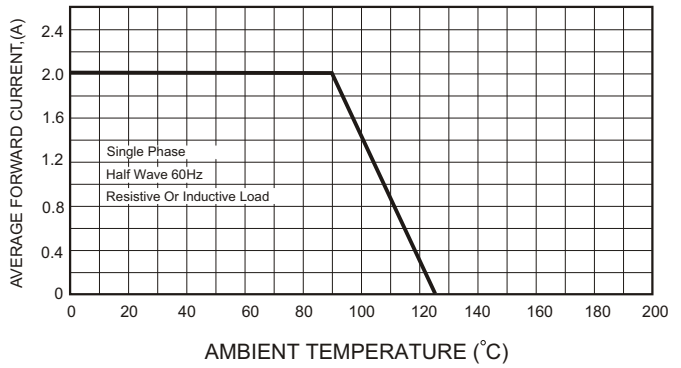


FIG.4-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

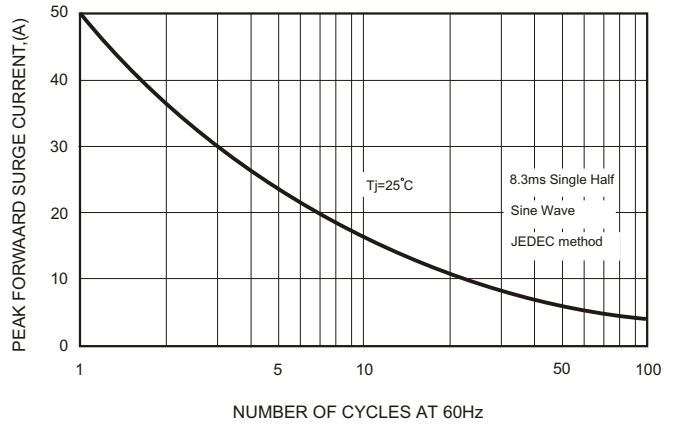


FIG.3 - TYPICAL REVERSE CHARACTERISTICS

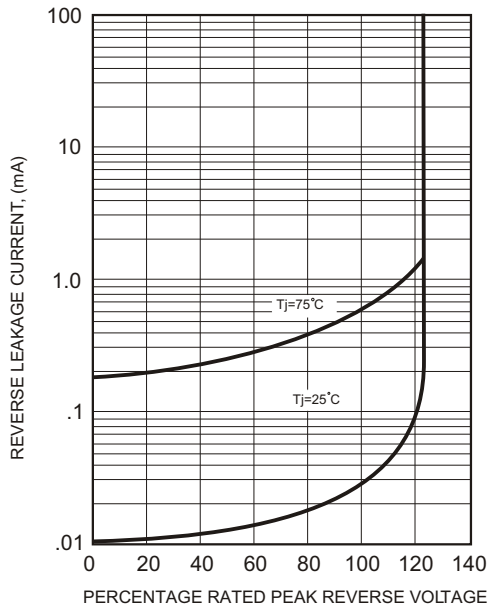


FIG.5-TYPICAL JUNCTION CAPACITANCE

